

ATTY, DKT. APPM/5699/CMP/CMP/RKK

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chen, et al.

Serial No.: 10/038,066

Filed:

January 3, 2002

Confirmation No.: 4101

For:

Planarization of Substrates

Using Electrochemical Mechanical Polishing

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

*ଊଊଊଊଊଊଊଊଊଊଊଊଊ* Group Art Unit: TONKHOWN

Examiner:

Unknown

**CERTIFICATE OF MAILING** 37 CFR 1.8

I hereby certify that this correspondence is being deposited on , 2002 with the United States Postal Service as First/Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on the date

Date

Signature

## INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possibly material information as defined under 37 CFR § 1.56(a) exists.

1

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

Respectfully submitted,

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